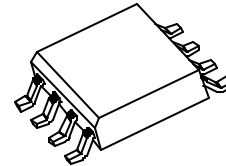
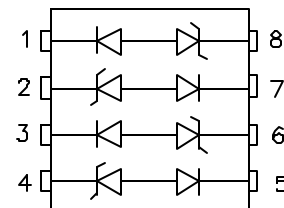


TECHNICAL DATA
DATA SHEET 1914, REV. -**TVS ARRAY SERIES****FEATURES**

- ✓ Protects 3.3, 5, 12, 15, 24 V Components
- ✓ Bidirectional
- ✓ Low Capacitance < 25 pF
- ✓ Provides Electrically Isolated Protection
- ✓ 500 W @ 8/20 μ s
- ✓ Protects 2 Lines
- ✓ SO-8 Packaging

SO-8**DESCRIPTION**

The S8CXX-2 series of TVS array have been designed to provide bidirectional protection for sensitive electronics from damage due to voltage transients caused by electrostatic discharge (ESD), electrical fast transients (EFT), lightning and other voltage-induced transient events. The device can be used to protect up to 2 bidirectional lines.

SCHEMATIC & PIN CONFIGURATION**APPLICATION**

- ✓ Portable Electronics
- ✓ USB, ADSL & SCSI Interface
- ✓ Cellular Phone Terminals
- ✓ Audio/Video Inputs
- ✓ LAN Interconnects

MECHANICAL CHARACTERISTICS

- ✓ SO-8 Surface Mount Package
- ✓ Approximate Weight: 0.1 grams
- ✓ Marking: Device number, Date code, & Logo
- ✓ PIN #1 Indicator: DOT on top of package
- ✓ Packaging: Tubes or Tape & Reel per EIA Standard 481

ABSOLUTE MAXIMUM RATINGS

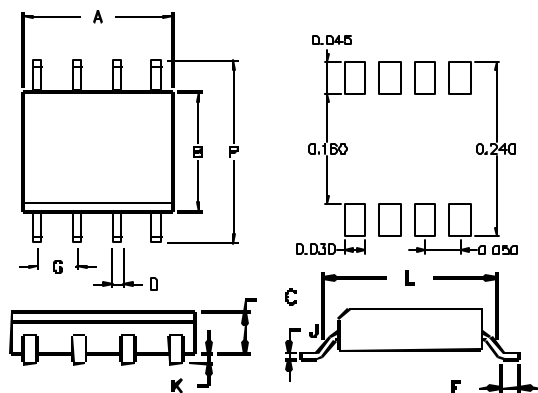
Symbol	Parameter	Value	Unit
P	Peak Pulse Power, 8/20 μ s Waveshape	500	W
T _J	Operating Temperature	-55 to +125	°C
T _{STG}	Storage Temperature	-55 to +150	°C
T _L	Lead Soldering Temperature	260 (10 Sec.)	°C

TECHNICAL DATA
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ELECTRICAL CHARACTERISTICS @ 25 °C

Part Number	Stand-off Voltage V_{wm} (v) Max	Breakdown Voltage V_{BR} @ 1mA (V) Min	Clamping Voltage V_c @ 1 A (V) Max	Leakage Current I_R @ V_{wm} (μ A) Max	Capacitance (f = 1MHz) C @ 0V (pF) Max	Temperature Coefficient of V_{BR} $a(V_{BR})$ mv/°C Max
S8C03-2	3.3	4	7	200	25	-5
S8C05-2	5.0	6	9.8	40	25	1
S8C12-2	12.0	13.3	19	1	25	8
S8C15-2	15.0	16.7	24	1	25	11
S8C24-2	24.0	26.7	43	1	25	28

PACKAGE OUTLINES & DEMENSIONS



DIM	INCHES		MILLIMETERS	
	MIN.	MAX	MIN.	MAX.
A	0.189	0.196	4.8	5.0
B	0.150	0.157	3.8	4.0
C	0.053	0.069	1.35	1.75
D	0.011	0.021	0.28	0.53
F	0.016	0.050	0.41	1.27
G	0.050 BSC		1.27 BSC	
J	0.006	0.010	0.15	0.25
K	0.004	0.008	0.10	0.20
L	0.189	0.206	4.80	5.23
P	0.228	0.244	5.79	6.19

TYPICAL CHARACTERISTICS

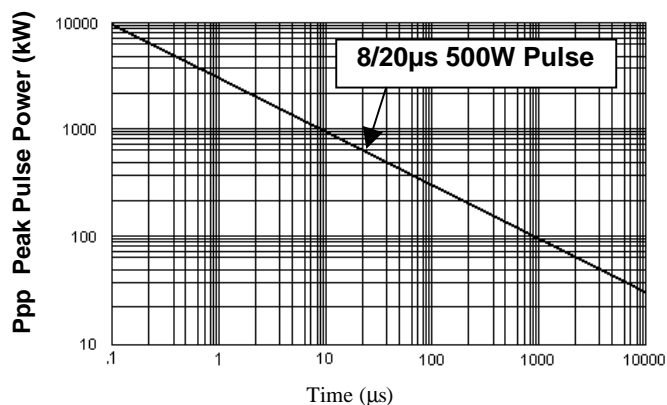


Figure 1. Peak Pulse Power Vs Pulse Time (ms)

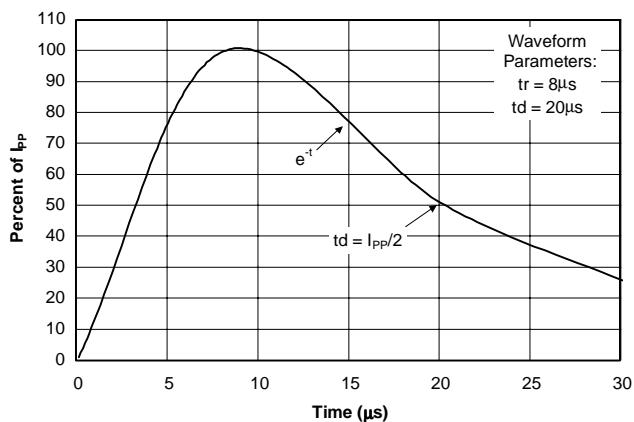


Figure 2. Pulse Wave Form

TECHNICAL DATA

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